

SPECIFICATION

00

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OLED SPECIFICATION

Model No:

REX009664BYAP3N00000

CUSTOMER:

APPROVED BY	,						
PCB VERSION							
DATE							
FOR CUSTOMER USE	EONLY	222					
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_APPROVAL FOR SPECIFICATIONS AND SAMPLE



1. Revision History

VERSION	DATE	REVISED PAGE NO.	Note	
0 A	2018/03/05 2018/11/27		First release Modify Static electricity test Content of Test	



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- 1.General Specification
- 2.Module Classification Information
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- 4.Contour Drawing & Block Diagram
- 5. Absolute Maximum Ratings
- **6.**Electrical Characteristics
- 7. Optical Characteristics
- 8.OLED Lifetime
- 9.Reliability
- 10.Inspection specification
- 11.Precautions in use of OLED Modules



1.General Specification

The Features is described as follow:

- Module dimension: 29.00 x 22.50 x 1.65 mm
- Active area: 22.53 x 15.01mm
- Dot Matrix: 96 x 64
- Dot size: 0.205 x 0.205 mm
- Dot pitch: 0.235 x 0.235 mm
- Display Mode : Passive Matrix
- Duty: 1/64 Duty
- Display Color: OLED , Yellow
- Controller IC: SSD1327
- Interface: 4-Wire SPI, I2C, 6800, 8080
- Size: 1.1 inch



2.Module Classification information

1	2	3	4	5	6	7	8	9	10	11	12	13	14
R	E	X	009664	В	Y	A	Р	3	N	0	0	0	00

	Drand · Davista		ropios Inc					
1	Brand : Raystar Optronics Inc.							
2	E : OLED							
		C : (COB Character			OB Graphic		
3			COG		H : C	OG + FR		
5	Display Type		COG + FR + PCB		T : T/	∖ B		
			COG + PCB			1		
4	Dot Matrix : 9	6*64						
5	Series							
			A : Amber	R : Red		C : Full Color		
•			B : Blue	W: White				
6	Emitting Color		G : Green	Y: Yellow				
			S : Sky Blue	X : Dual Color				
7	Delevizer		P: With Polarizer;	P: With Polarizer; N: Without Polarizer				
7	Polarizer		A : Anti-glare Polar	izer				
8	Display Mode)	P : Passive Matrix	; N: Active Matri	х			
9	Driver Voltage	4	3:3.0~3.3V ; 5	: 5.0V				
10	Touch Panel	A	N: Without touch p	anel; T: With tou	ch pane			
		Y,	0 : Standard					
	Product type		1 : Daylight Readal					
11	F TOULOU LYPE		2 : Transparent OL	· · · · ·				
			3 : Flexible OLED (FOLED)				
	Y Y		4 : OLED Lighting					
			0 : Standard					
12	Inspection Gra	do	2 : B grade					
12	moposition dia	uc	C: Automotive grad					
			Y: Consumer grad					
13	Option		0 : Default ; F : ZIF		ar FPC	; D : Demo Kit		
14	Serial No.		Serial number(00~2	ZZ)	2	100000		
L					10			



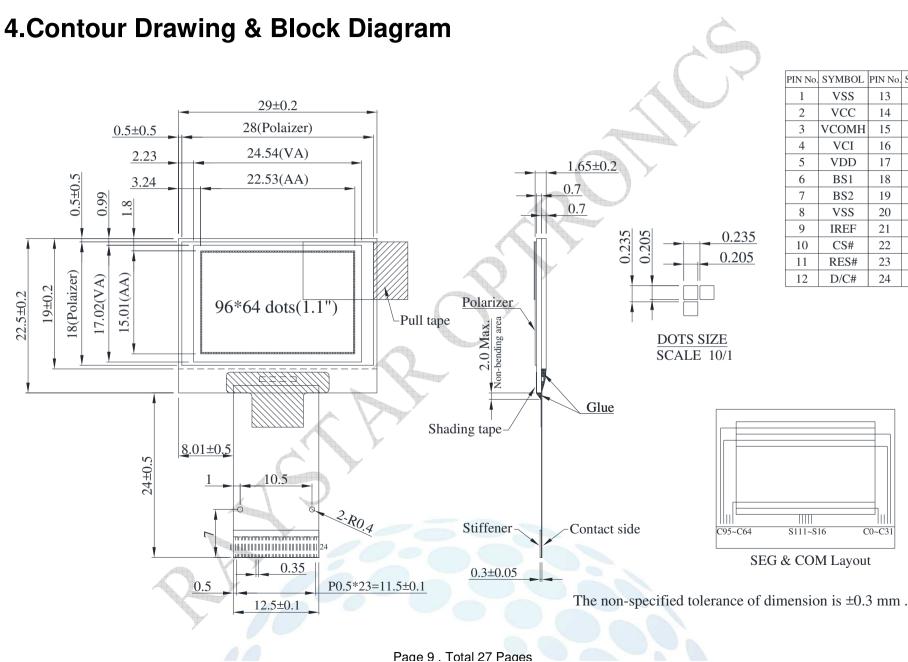
3.Interface Pin Function

No.	Symbol	Function
1	VSS	Ground pin. It must be connected to external ground.
2	VCC	Power supply for panel driving voltage. This is also the most positive power
2	VCC	voltage supply pin. It is supplied by external high voltage source.
		COM signal deselected voltage level.
3	VCOMH	A capacitor should be connected between this pin and VSS. No external power
		supply is allowed to connect to this pin.
		Low voltage power supply and power supply for interface logic level. It should
4	VCI	match with the MCU interface voltage level and must be connected to external
•		source.
		VCI must always set to be equivalent to or higher than VDD.
5	VDD	Power supply pin for core logic operation.
		MCU bus interface selection pins. Select appropriate logic setting as described
		in the following table. BS2 and BS1 are pin select.
6	BS1	Bus Interface selection
		BS[2:1] Interface
		00 4 line SPI 01 I2C
		11 8-bit 8080 parallel
7	BS2	10 8-bit 6800 parallel
	_	Note (1) 0 is connected to VSS (2) 1 is connected to VCI
8	VSS	Ground pin. It must be connected to external ground.
9	IREF	This pin is the segment output current reference pin
•		This pin is the chip select input connecting to the MCU.
10	CS#	The chip is enabled for MCU communication only when CS# is pulled LOW
		(active LOW).
		This pin is reset signal input.
11	RES#	When the pin is pulled LOW, initialization of the chip is executed.
	1	Keep this pin pull HIGH during normal operation.
		This pin is Data/Command control pin connecting to the MCU.
		When the pin is pulled HIGH, the data at D[7:0] will be interpreted as data.
12	D/C#	When the pin is pulled LOW, the data at D[7:0] will be transferred to a command
	0/0#	register.
		In I2C mode, this pin acts as SA0 for slave address selection.
\sim		When 3-wire serial interface is selected, this pin must be connected to VSS.
V		This pin is read / write control input pin connecting to the MCU interface.
		When 6800 interface mode is selected, this pin will be used as Read/Write
		(R/W#) selection input. Read mode will be carried out when this pin is pulled
13	R/W#	HIGH and write mode when LOW.
		When 8080 interface mode is selected, this pin will be the Write (WR#) input.
		Data write operation is initiated when this pin is pulled LOW and the chip is
		selected.
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14	E	This pin is MCU interface input. When 6800 interface mode is selected, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled HIGH and the chip is selected. When 8080 interface mode is selected, this pin receives the Read (RD#) signal. Read operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I2C interface is selected, this pin must be connected to VSS.
15	D0	
16	D1	These pins are bi-directional data bus connecting to the MCU data bus.
17	D2	Unused pins are recommended to tie LOW.
18	D3	When serial interface mode is selected, D0 will be the serial clock input: SCLK;
19	D4	D1 will be the serial data input: SDIN and D2 should be kept NC.
20	D5	When I2C mode is selected, D2, D1 should be tied together and serve as
21	D6	SDAout, SDAin in application and D0 is the serial clock input, SCL.
22	D7	
23	VCC	Power supply for panel driving voltage. This is also the most positive power voltage supply pin. It is supplied by external high voltage source.
24	VSS	Ground pin.





PIN No. SYMBOL

R/W#

Е

D0

D1

D2

D3

D4

D5

D6

D7

VCC

VSS

13

14

15

16

17

18

19

20

21

22

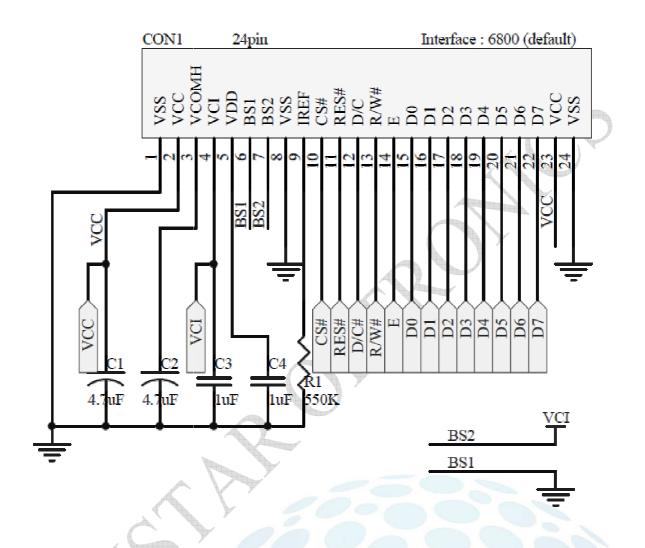
23

24

C0~C31



4.1 Application recommendations



*For more information, please refer to Application Note provided by Raystar Optronics.



5.Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Operation	VCI	-0.3	4.0	V	1, 2
Supply Voltage for Logic	VDD	-0.5	2.75	V	1, 2
Supply Voltage for Display	VCC	-0.5	19.0	V	1, 2
Operating Temperature	TOP	-40	+80	°C	-
Storage Temperature	TSTG	-40	+85	°C	-

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.

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6.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VCI	_	2.8	3.0	3.3	v
Supply Voltage for Display	VCC	—	8.0	8.5	9.0	V
Input High Volt.	VIH	—	0.8×VCI	t	VCI	V
Input Low Volt.	VIL	—	VSS	\rightarrow	0.2×VCI	V
Output High Volt.	VOH	_	0.9×VCI		VCI	V
Output Low Volt.	VOL	-	VSS	_	0.1×VCI	V
50% Check Board operating Current	ICC	VCC=8.5V	<i>y</i>	13.0	26.0	mA

6.1 DC Electrical Characteristics



6.2 Initial code

void Initial(void)

{

//Set Command Lock
Write_command(0xfd);
Write_command(0x12);

Write_command(0xae);

//Set Contrast current
Write_command(0x81);
Write_command(0xFF);

//Set Re-map
Write_command(0xa0);
Write_command(0x51);

Write_command(0xa4);

Write_command(0xa8); Write_command(63);

//Function Selection
Write_command(0xab);
Write_command(0x01);

//Set Phase Length
Write_command(0xb1);
Write_command(0x22);

//Set Front Clock Divider/Oscillator Frequency
Write_command(0xb3);
Write_command(0xF0);

//Set Second pre-charge Period
Write_command(0xb6);
Write_command(0x0f);

Write_command(0xbc); Write_command(0x07);

Write_command(0xbe); Write_command(0x07);

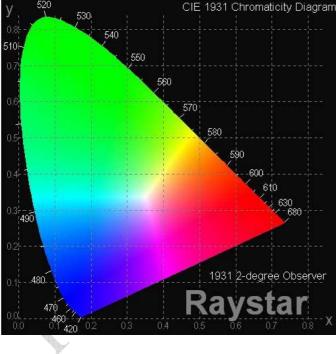
Write_command(0xD5); Write_command(0x62);

Write_command(0xaf);



7.Optical Characteristics

Symbol	Condition	Min	Тур	Мах	Unit
(V)θ	—	160	—	—	deg
(H)φ	_	160	_	X	deg
CR	Dark	2000:1	- 🖌	-	
T rise	_	_	10		μs
T fall	_	_	10	_	μs
check Board Bri	ghtness	60	80		cd/m2
CIEx(Yellow) (CIE1931)			0.47	0.49	_
CIEy(Yellow)			0.50	0.52	_
	(V)θ (H)φ CR T rise T fall check Board Bri	(V)θ-(H)φ-CRDarkT rise-T fall-check Board Brightnessw)(CIE1931)	(V)θ - 160 (H)φ - 160 CR Dark 2000:1 T rise - - T fall - - check Board Brightness 60 w) (CIE1931) 0.45	(V)θ - 160 - (H)φ - 160 - CR Dark 2000:1 - T rise - - 10 T fall - - 10 check Board Brightness 60 80 w) (CIE1931) 0.45 0.47	(V)θ - 160 - (H)φ - 160 - CR Dark 2000:1 - Trise - - T fall - - Check Board Brightness 60 80 N) (CIE1931) 0.45 0.47





8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°C / Initial 50% check board brightness Typical Value	50,000 Hrs	-	Note

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.



9.Reliability

Content of Reliability Test

Environmenta			Applicable
Test Item	Content of Test	Test Condition	Standard
High Temperature storage	Endurance test applying the high storage temperature for a long time.	85°C 240hrs	-
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40°C 240hrs	
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80°C 240hrs	\
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40°C 240hrs	
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60°C,90%RH 240hrs	
High Temperature/ Humidity Operation	Endurance test applying the high temperature and high humidity Operation for a long time.	60°C,90%RH 120hrs	
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min 5min 30min 1 cycle	-40°C /80°C 30 cycles	
Mechanical Tes	st C		
Vibration test	Endurance test applying the vibration during transportation and using.	Frequency:10~55Hz amplitude:1.5mm Time:0.5hrs/axis Test axis:X,Y,Z	
Others			
Static electricity test	Endurance test applying the electric stress to the finished product housing.	Air Discharge model ±4kv,10 times	

*** Supply voltage for OLED system =Operating voltage at 25°C



Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

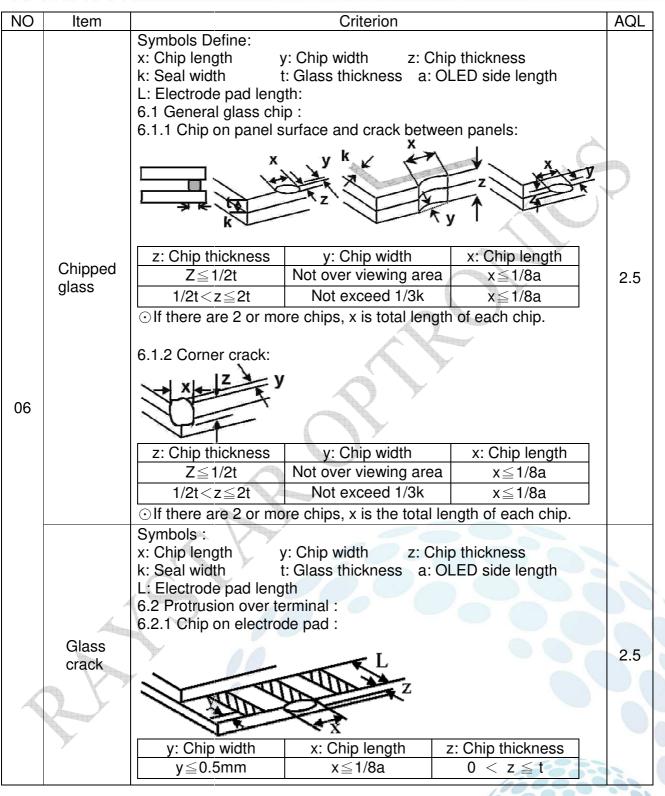
Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



10.Inspection specification

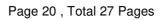
NO	Item		Criterion		AQL	
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 				
02	Black or white spots on OLED (display only)	2.1 White and black spots on three white or black spots pre2.2 Densely spaced: No more	esent.	A A	2.5	
03	OLED black spots, white spots, contamin ation (non-disp lay)			Acceptable QTY Accept no dense 2 1 0	2.5	
		3.2 Line type : (As following d Length L≦3.0 L≦2.5 	Width W≦0.02	Acceptable Q TY Accept no dense 2 As round type	2.5	
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.		Acceptable Q TY Accept no dense 3 2 0 3 3	2.5	
05	Scratches	Follow NO.3 OLED black spo	ts, white spots, co	ntamination.	,ée,	







NO	Item	Criterion	AQL
06	Glass crack	Criterion6.2.2 Non-conductive portion: y y x x y x y x $y \leq L$ $x \leq 1/8a$ $0 < z \leq t$ 0	2.5
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65





NO	Item	Criterion	AQL
		10.1 COB seal may not have pinholes larger than 0.2mm or contamination.	2.5
		10.2 COB seal surface may not have pinholes through to the IC.	2.5
		10.3 The height of the COB should not exceed the height	0.65
	PCB, COB	indicated in the assembly diagram.	2.5
		10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than	2.5
10		three places. 10.5 No oxidation or contamination PCB terminals.	2.5
		10.6 Parts on PCB must be the same as on the production	2.5 0.65
		characteristic chart. There should be no wrong parts, missing parts or excess parts.	0.00
		10.7 The jumper on the PCB should conform to the product	0.65
		characteristic chart.	
		10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or	2.5
		screw hold pad, make sure it is smoothed down.	
		11.1 No un-melted solder paste may be present on the PCB.	2.5
		11.2 No cold solder joints, missing solder connections, oxidation	2.5
11	Soldering	or icicle.	
		11.3 No residue or solder balls on PCB.	2.5
		11.4 No short circuits in components on PCB.	0.65
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
	4	12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface	2.5
	General	pin must be present or look as if it cause the interface pin to	
12	appearance	Sever.	0.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	2.5
	K	12.8 Pin type must match type in specification sheet.	0.65
		12.9 OLED pin loose or missing pins.	0.65
	Ŧ	12.10 Product packaging must the same as specified on	0.65
		packaging specification sheet.	
		12.11 Product dimension and structure must conform to product	0.65
		specification sheet.	



Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Short	Major	
Wrong Display	Major	
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major	A Normal B Dark Pixel C Light Pixel



11.Precautions in use of OLED Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist OLED display module.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9) Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time.
- (10) Raystar has the right to change the passive components, including R2and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)

(11) Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)

11.1 Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
- * Scotch Mending Tape No. 810 or an equivalent

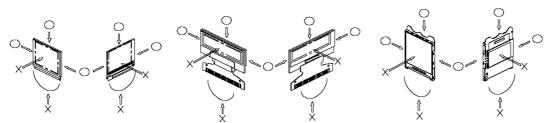
Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent Also, pay attention that the following liquid and solvent may spoil the polarizer:

* Water

* Ketone

- * Aromatic Solvents
- (6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.

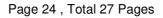




- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
- * Be sure to make human body grounding when handling OLED display modules.
- * Be sure to ground tools to use or assembly such as soldering irons.
- * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

11.2 Storage Precautions

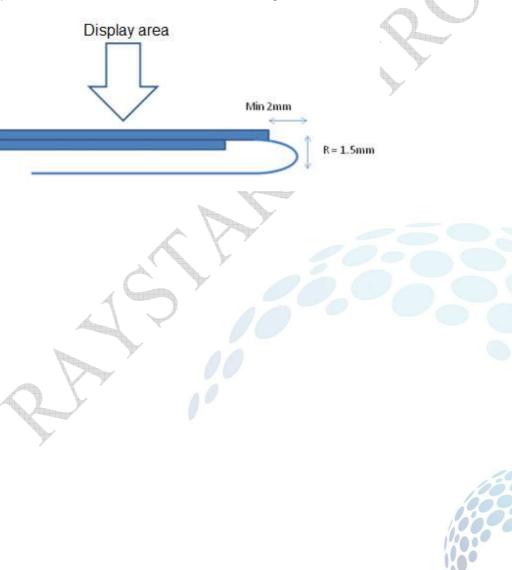
- (1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. And, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments.(We recommend you to store these modules in the packaged state when they were shipped from Raystar Optronics Inc. At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
- (2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.





11.3 Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module. Connection (contact) to any other potential than the above may lead to rupture of the IC.
- (8) The limitation of FPC and Film bending.





		Page: 1
<u>Modu</u>	le Sample	e Estimate Feedback Sheet
Module Number :		
1 <u>Panel Specification</u>		
1. Panel Type :	□ Pass	□NG ,
2. Numbers of Pixel :		□NG ,
3. View Area :		□NG ,
4. Active Area :		□NG ,
5.Emitting Color :		□NG ,
6.Uniformity :	□Pass	□NG ,
7.Operating Temperature :	Pass	□NG ,
8.Storage Temperature :	Pass	□NG ,
9.Others :		
2 · Mechanical Specificati	on :	
1. PCB Size :	□Pass	□NG ,
2.Frame Size :	□Pass	□NG ,
3.Materal of Frame :	□Pass	□NG ,
4.Connector Position :	□Pass	□NG ,
5.Fix Hole Position :	□Pass	□NG ,
6. Thickness of PCB :	□Pass	□NG ,
7. Height of Frame to PCB :	□Pass	□NG ,
8.Height of Module :	□Pass	□NG ,
9.Others :	□Pass	□NG ,
3 · <u>Relative Hole Size</u> :		
1.Pitch of Connector :	□Pass	□NG ,
2.Hole size of Connector :	□Pass	□NG ,
3.Mounting Hole size :	□Pass	□NG ,
4.Mounting Hole Type :	□Pass	□NG ,
5.Others :	□Pass	□NG ,

>> Go to page 2 <<



Module Number :			
4 · <u>Electronic Characterist</u>			
1.Input Voltage :	□Pass	□NG ,	
2.Supply Current :	□Pass	□NG ,	
3.Driving Voltage for	□Pass	□NG ,	
OLED :			
4.Contrast for OLED :	□Pass	□NG ,	
5.Negative Voltage	□Pass	□NG ,	
Output :	Dese		
6.Interface Function :	□Pass	□NG ,	
7.ESD test :	□Pass	DNG ,	
8.Others : 5 \ <u>Summary</u> :	□Pass	□NG ,	
Sales signature : _			
Sales signature :	e :		